

| L Number | Hits | Search Text | DB | Time stamp |
|---------------------|-------------|---|---|---------------------|
| - | 2 | 6195878.pn. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/21 08:56 |
| - | 9 | microcircuit and stackable | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:06 |
| - | 3 | microcircuit and stackable and (361/743, 257/E23.063 , 257/E25.023 , 29/830 , 29/840 , 29/841, 361/735 , 361/746).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:11 |
| - | 5 | microcircuit and stackable and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:12 |
| - | 1 | microcircuit same stackable and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:12 |
| - | 8427 | microcircuit adj1\$ stackable and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:13 |
| - | 0 | microcircuit adj stackable and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:12 |
| - | 827994 | microcircuit adj\$3 stackable and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:13 |

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| - | 8267 | microcircuit adj1\$ stackable and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls. and 29/830.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:13 |
| - | 8266 | microcircuit adj1\$ stackable and PEM and I/O near pad and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:14 |
| - | 8266 | microcircuit adj1\$ stackable and PEM and " I/O near pad" and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:14 |
| - | 8266 | microcircuit adj1\$ stackable and PEM same " I/O near pad" and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803, 439/66 , 439/91).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:15 |
| - | 0 | microcircuit near stackable and PEM same " I/O near pad" and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803, 439/66 , 439/91).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:15 |
| - | 0 | microcircuit and PEM same " I/O near pad" and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803, 439/66 , 439/91).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:15 |
| - | 1 | microcircuit and PEM and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803, 439/66 , 439/91).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:15 |

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|---|-----|---|---|---------------------|
| - | 19 | microcircuit and encapsulate\$3 and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803, 439/66 , 439/91).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:27 |
| - | 9 | ("4574331" "4581675" "4764846" "5007841" "5027191" "5043794" "5241456" "5376825" "5432681").PN. | USPAT | 2003/11/25 09:18 |
| - | 398 | 29/855.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 09:28 |
| - | 0 | microcircuit and encapsulant and IC and pads and 29/855.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 10:43 |
| - | 21 | microcircuit and encapsulant and bare same die and pads | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 11:18 |
| - | 19 | ("4462534" "5024372" "5220200" "5261593" "5293067" "5346861" "5381848" "5388327" "5455390" "5504277" "5539153" "5541460" "5547740" "5564617" "5604379" "5608262" "5701032" "5736456" "5814894").PN. | USPAT | 2003/11/25 10:45 |
| - | 10 | ("4989063" "5442240" "5450283" "5497033" "5554887" "5641996" "5650593" "5656863" "5677566" "5684330").PN. | USPAT | 2003/11/25 10:49 |
| - | 12 | ("5136366" "5239198" "5289346" "5293072" "5341564" "5355283" "5362679" "5397921" "5420460" "5442231" "5442233" "5519251").PN. | USPAT | 2003/11/25 11:05 |
| - | 10 | ("3969813" "4012832" "5424254" "5436202" "5696033" "5700697" "6054012" "6335629" "6358852" "6368886").PN. | USPAT | 2003/11/25 11:13 |
| - | 23 | ("H001379" "3482419" "3627901" "3762039" "3969813" "4089704" "4359360" "4384917" "4474621" "4567006" "4691225" "4768286" "4914813" "4980019" "5041396" "5138430" "5149662" "5155068" "5180093" "5252179" "5398926" "5406117" "5424254").PN. | USPAT | 2003/11/25 11:17 |

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| - | 0 | microcircuit and encapsulant and bare same die and pads and peter near vo .XP. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 11:19 |
| - | 2 | microcircuit and encapsulant and bare same die and pads and 29/\$.ccis. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 11:20 |
| - | 2 | 5424154.pn. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 12:48 |
| - | 2 | 5424254.pn. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 12:50 |
| - | 1 | 1995-223702.NRAN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 12:48 |
| - | 4 | bare same semiconductor near chip and plastic adj package and recovering | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 13:01 |
| - | 0 | 20020048825.URPN. | USPAT | 2003/11/25 12:52 |
| - | 10 | ("3969813" "4012832" "5424254" "5436202" "5696033" "5700697" "6054012" "6335629" "6358852" "6368886").PN. | USPAT | 2003/11/25 12:53 |
| - | 31 | ("3969813" "4043080" "4063542" "4089704" "4213698" "4344809" "4359360" "4384917" "4822441" "4826556" "4992135" "5193314" "5223083" "5252179" "5271798" "5291693" "5443675" "5479108" "5585675" "5611876" "5703493" "5750423" "5766496" "5783098" "5792305" "5855727" "5915370" "5932061" "5964646" "6033933" "6055976").PN. | USPAT | 2003/11/25 12:54 |
| - | 20 | 5424254.URPN. | USPAT | 2003/11/25 12:55 |
| - | 1 | bare same semiconductor near chip and plastic adj package and I/O near pads | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 13:03 |

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| - | 1 | providing adj plastic near package and I/O near pads | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 13:04 |
| - | 1 | providing adj plastic near package and I/O | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 13:04 |
| - | 1 | providing adj plastic same package and I/O | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 13:04 |
| - | 19 | providing adj plastic same package and pads | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 13:07 |
| - | 3 | providing adj plastic same package and modifying | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 13:10 |
| - | 29 | providing adj plastic same package and modification | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/25 13:10 |